



Final Product Change Notification

201409012F01

Issue Date: 15-Dec-2014
Effective Date: 30-Mar-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input checked="" type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Introduce Manchester UK as a source for TrenchMOS 6 LFPAK56 & LFPAK56D Auto Products

Details of this Change

Products made using the T6 TrenchMOS silicon process sourced from Global Foundries, Singapore, have been qualified in to the NXP Manchester UK Fab.

This FPCN installment (PCN 201409012F01) is to cover LFPAK56 types. A further iteration will be issued to cover LFPAK56D at a later date.

Please refer to the attached supporting documentation for further details regarding this change.

Why do we implement this Change

Further to the introduction of T6 supplied from Singapore, NXP is now extending this source capability to the latest T6 designs in automotive packages from the Manchester fab. Manchester will be the primary diffusion site from January 2015.

Identification of Affected Products

Top side marking

Devices from Manchester will be identified by 'E'

Product Availability

Sample Information

Samples availability differs by product - see attached sample plan

Samples availability, please refer to section14 (updated) of the attached supporting documentation

Production

Planned first shipment 30-Mar-2015

Impact

no impact to the product's functionality anticipated.

- The constituent layers and the physical dimensions of finished devices will be identical.
- The finished products will be electrically equivalent on all parameters, both static and dynamic.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

N/A

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Jan-2015.

Remarks

Samples of Manchester product can be requested via t6.sample@nxp.com

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address t6.sample@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP | Privacy Policy | Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.